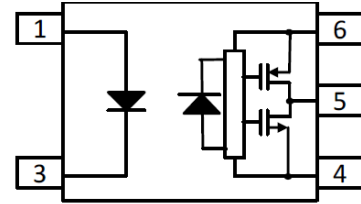


● Description

The KPC315 series consists of an infrared light emitter diode and an integrated circuit with a power output stage.

This unit is SOP 5pin package. KPC315 series is suitable for gate driving circuit of IGBT or power MOSFET.

● Schematic



1. Anode

4. GND

3. Cathode

5. Vo (Voltage Output)

6. Vcc

● Features

1. Input threshold current: $I_F=5\text{mA}(\text{max.})$
2. Supply current (I_{CC}): 3 mA (max.)
3. Supply voltage (V_{CC}): 10 – 30V
4. Output current (I_O): 1.0A (max.)
5. Switching time (t_{pLH}/t_{pHL}): 0.5 $\mu\text{s}(\text{max.})$
6. Isolation voltage: 3750Vrms(min.)
7. Agency Approvals:
 - UL Approved
 - c-UL Approved
 - VDE Approved

● Applications

- Transistor inverter
- Inverter for air conditioner
- IGBT gate drive
- Power MOSFET gate drive
- IH(Induction Heating)

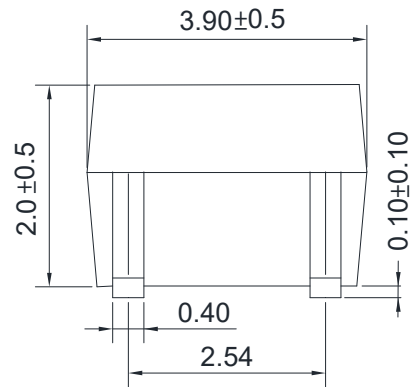
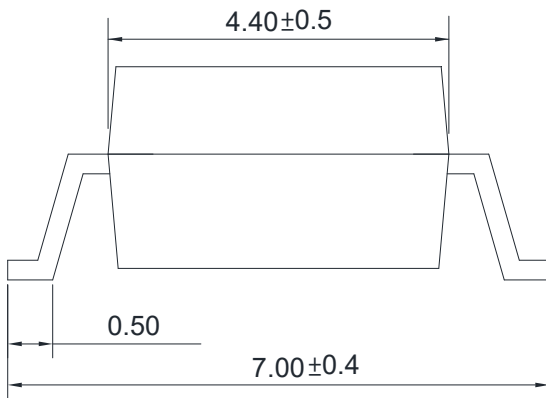
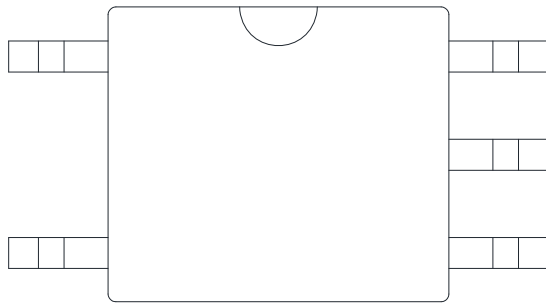
● Truth Table

LED	OUTPUT	Q1	Q2
ON	HIGH LEVEL	ON	OFF
OFF	LOW LEVEL	OFF	ON

* The use of a 0.1 μF bypass capacitor must be connected between pins 4 and 6 is recommended.

● **Outside Dimension**

Unit : mm



TOLERANCE: ±0.2mm

● **Device Marking**



Notes:

Cosmo
315
YWW

Y: Year code / WW: Week code

● Absolute Maximum Ratings

(Ta = 25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	20	mA
	Peak transient forward current (*Note 1)	I_{FPT}	1	A
	Reverse voltage	V_R	5	V
	Junction temperature	T_j	125	°C
Output	"H" Peak output current (*Note 2)	I_{OPH}	-1	A
	"L" Peak output current (*Note 2)	I_{OPL}	+1	A
	Output voltage	V_O	30	V
	Supply voltage	V_{CC}	30	V
	Junction temperature	T_j	125	°C
Operating frequency (*Note 3)		f	50	KHz
Operating temperature range		T_{opr}	-40~110	°C
Storage temperature range		T_{stg}	-55~125	°C
Lead soldering temperature(10s) (*Note 4)		T_{sol}	260	°C
Isolation voltage (AC, 1min., R.H ≤ 60%) (*Note 5)		BVs	3750	Vrms

*Note1: Pulse width $Pw \leq 1\mu s, 300pps$.

*Note2: Exponential waveform pulse width $Pw \leq 2\mu s, f \leq 10kHz, V_{CC}=20V$.

*Note3: Exponential waveform, $I_{OPH} \geq -2.0A (\leq 0.3\mu s), I_{OPL} \leq +2.0A (\leq 0.3\mu s)$.

*Note4: It is 2 mm or more from a lead root.

*Note5: Device is considered as a two terminal device: Pin1 and 3 shorted together, and pins 4, 5 and 6 shorted together.

● Recommend Operation Conditions

Parameter	Symbol	Min.	Max.	Unit
Operating Temperature	T_A	-40	110	°C
Supply Voltage	V_{CC}	10	30	V
Input Current (ON)	$I_{F(ON)}$	7	16	mA
Input Voltage (OFF)	$V_{F(OFF)}$	0	0.8	V

● Electrical Characteristics

(Ta = 25°C)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input forward voltage		V_F	$I_F=10\text{mA}$	1.0	1.4	1.8	V
Temperature coefficient of forward voltage		$\Delta V_F/\Delta T_a$	$I_F=10\text{mA}$	—	-1.4	—	mV/°C
Input reverse current		I_R	$V_R=5\text{V}$	—	—	10	μA
Input capacitance		C_T	$V=0, f=1\text{MHz}$	—	45	250	pF
Output current*	“H” level	I_{OH}	$V_{CC}=30\text{V } I_F=5\text{mA } V_o=V_{CC}-1$	—	—	-0.3	A
			$V_{CC}=30\text{V } I_F=5\text{mA } V_o=V_{CC}-4$	—	—	-1.0	
	“L” level	I_{OL}	$V_{CC}=30\text{V } I_F=0\text{mA } V_o=V_{CC}+1$	0.3	—	—	
			$V_{CC}=30\text{V } I_F=0\text{mA } V_o=V_{CC}+4$	1.0	—	—	
Output voltage	“H” level	V_{OH}	$I_F=10\text{mA}, I_O=-100\text{mA}$	$V_{CC}-0.3$	$V_{CC}-0.1$	—	V
	“L” level	V_{OL}	$I_F=0\text{mA}, I_O=100\text{mA}$	—	0.3	1.0	
Supply current	“H” level	I_{CCH}	$V_{CC}=30\text{V}, I_F=10\text{mA}$	—	1.7	3.0	mA
	“L” level	I_{CCL}	$V_{CC}=30\text{V}, I_F=0\text{mA}$	—	2.1	3.0	
Threshold input current	“Output L→H”	I_{FLH}	$V_{CC}=15\text{V}, V_o>1\text{V}$	—	2.6	5	mA
Threshold input voltage	“Output H→L”	V_{FHL}	$V_{CC}=15\text{V}, V_o>1\text{V}$	0.8	—	—	V
Under voltage lockout threshold		V_{UVLO+}	$I_F=10\text{mA}, V_o>5\text{V}$	6.9	7.8	8.7	V
		V_{UVLO-}	$I_F=10\text{mA}, V_o<5\text{V}$	5.9	6.7	7.5	
Under voltage lockout threshold hysteresis		$UVLO_{HYS}$		—	1.1	—	V
Supply voltage		V_{CC}		10	—	30	V

*Maximum pulse width= 10us, maximum duty cycle =1.1%.

● Switching Characteristics

(Ta = 25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit	
Propagation delay time	“L→H”	$I_F=5mA$ $V_{CC}=30V$ $R_g=20\Omega, C_g=10nF$	50	130	500	ns	
	“H→L”		50	110	500		
Output rise time	t_r		—	8	—		
Output fall time	t_f		—	5	—		
Common mode transient immunity at high level output	$ C_{MH} $		$V_{CM}=1000Vp-p, I_F=5mA$ $V_{CC}=30V, V_o(min)=26V$	20	—	—	KV/ μs
Common mode transient immunity at low level output	$ C_{ML} $		$V_{CM}=1000Vp-p, I_F=0$ $V_{CC}=30V, V_o(max)=1V$	20	—	—	KV/ μs

TYPICAL PERFORMANCE CURVES & TEST CIRCUITS

Fig.1 High output rail voltage vs. Temperature

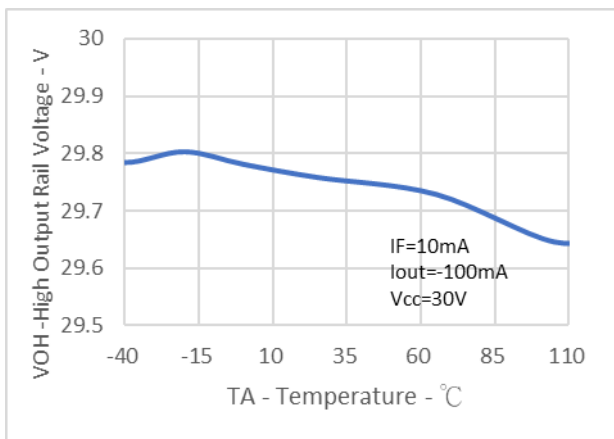


Fig.2 V_{OH} vs. Temperature

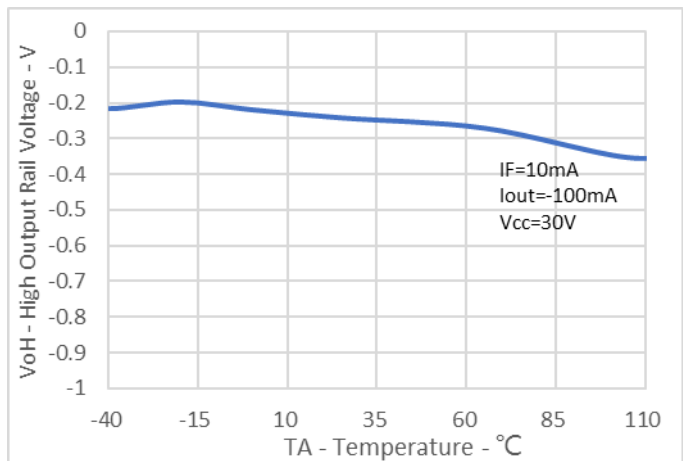


Fig.3 VOL vs. Temperature

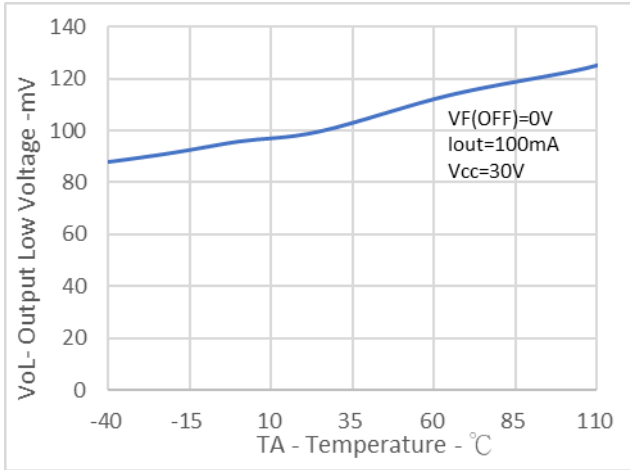


Fig.4 ICC vs. Temperature

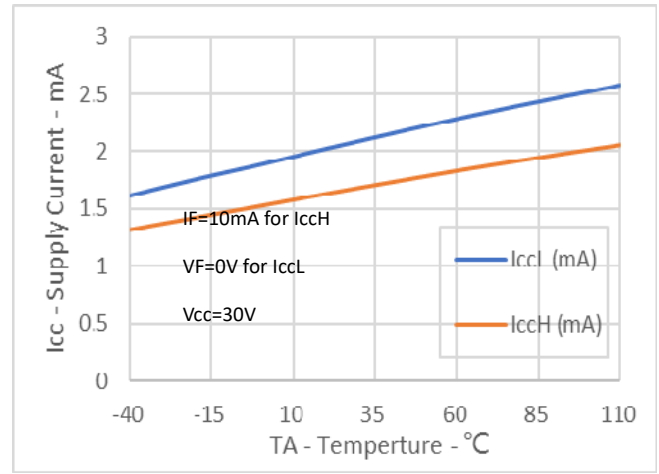


Fig.5 ICC vs. VCC

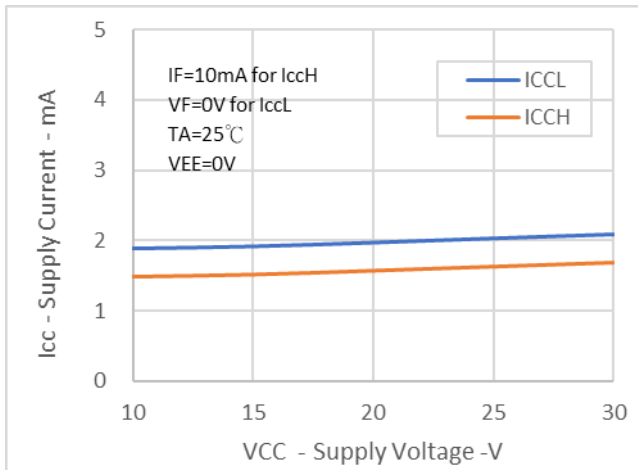


Fig. 6 IFLH Hysteresis

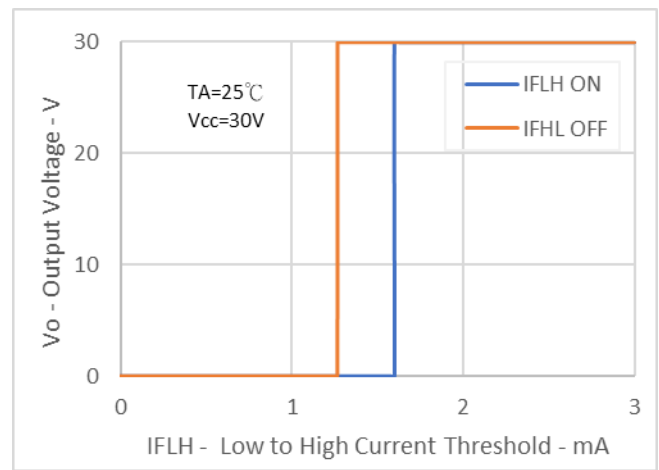


Fig.7 IFLH vs. Temperature

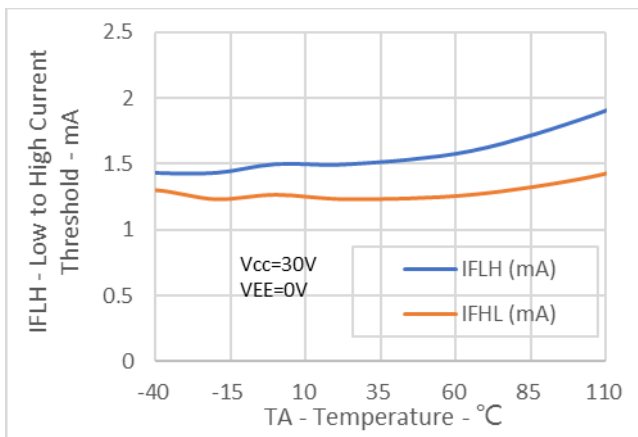


Fig.8 Propagation Delays vs. VCC

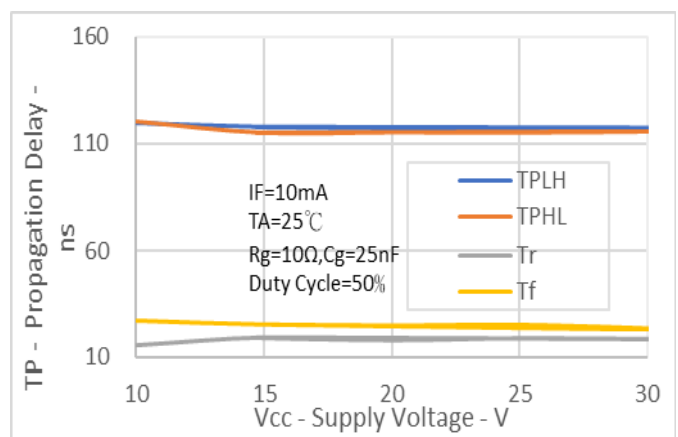


Fig.9 Propagation Delays vs. IF

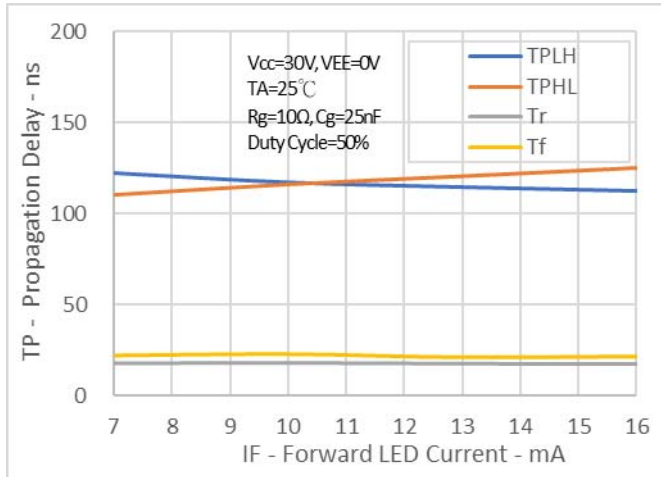


Fig.10 Propagation Delays vs. Temperature

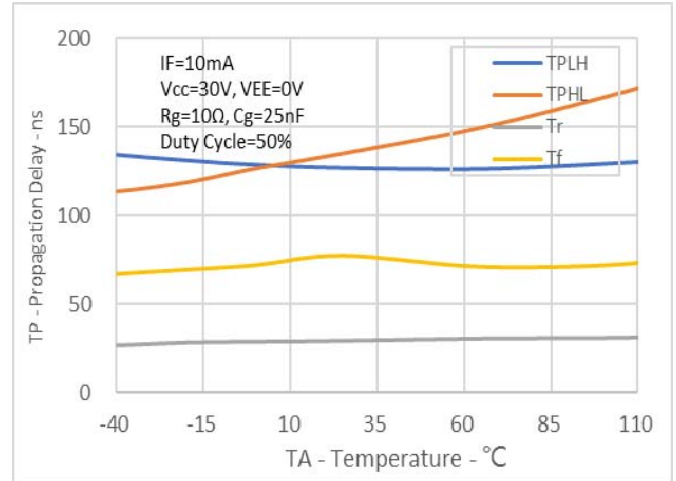


Fig.11 Propagation Delay vs Rg

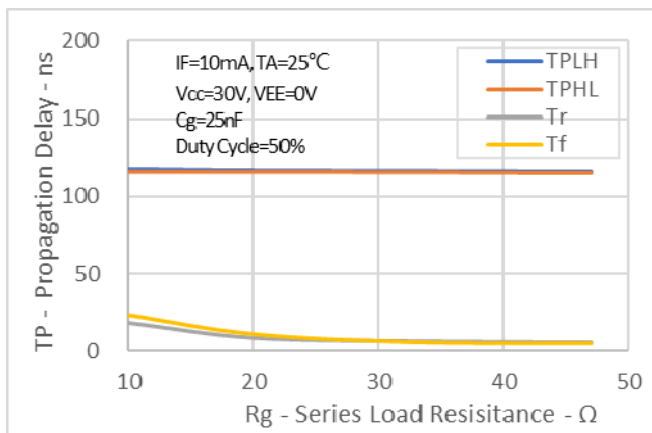


Fig. 12 Propagation Delay vs. Cg

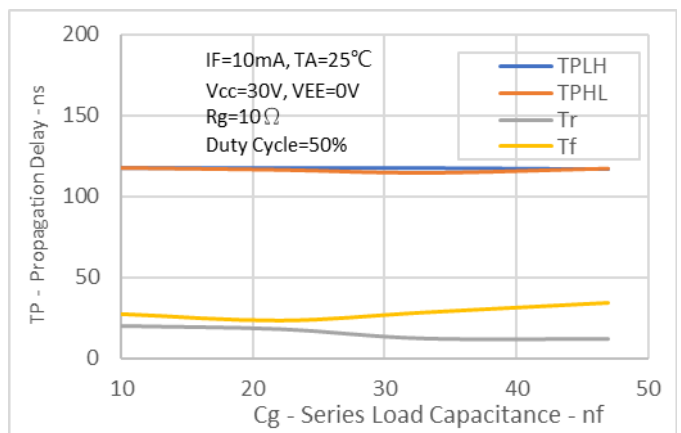
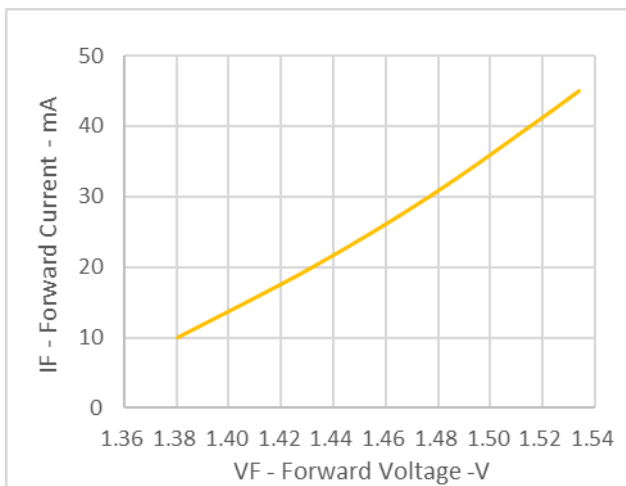
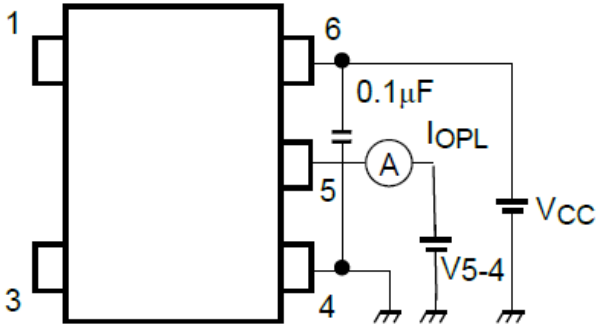


Fig.13 Input Current vs. Forward Voltage

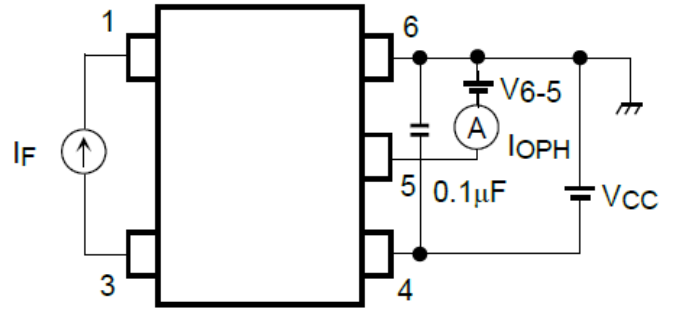


● Test Circuit

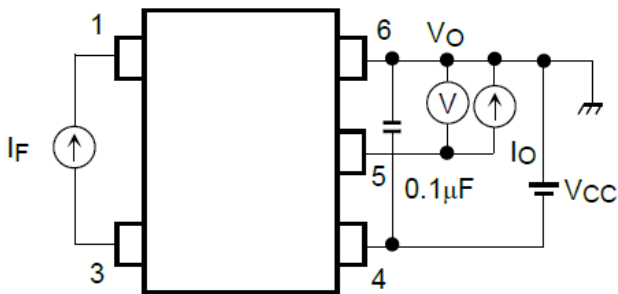
1. I_{OPL} Measure



2. I_{OPH} Measure

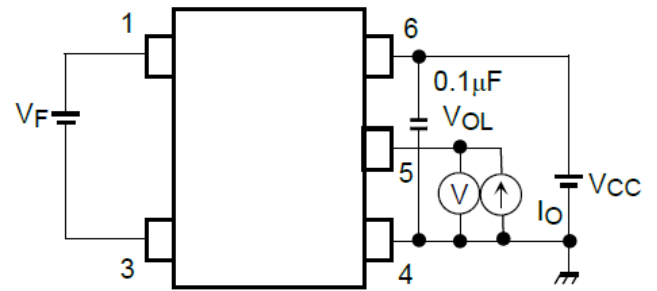


3. V_{OH} Measure

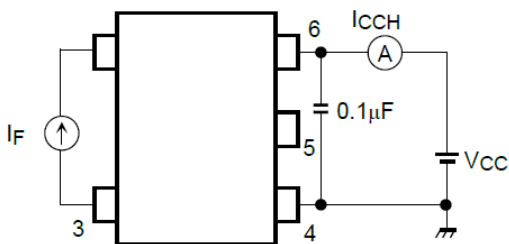


* $V_{OH} = V_{CC} - V_O$

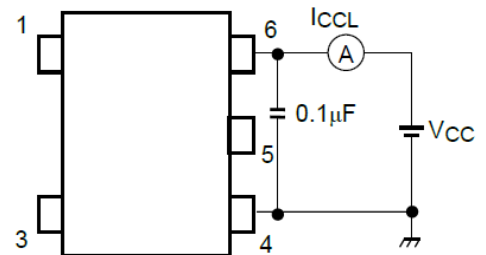
4. V_{OL} Measure



5. I_{CCH} Measure

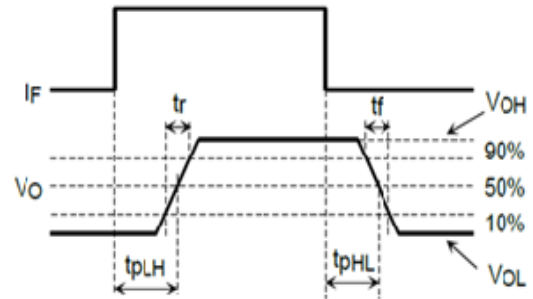
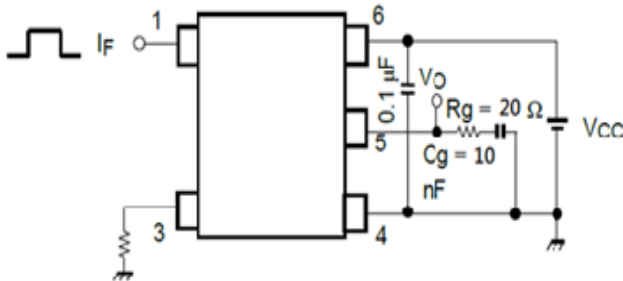


6. I_{CCL} Measure

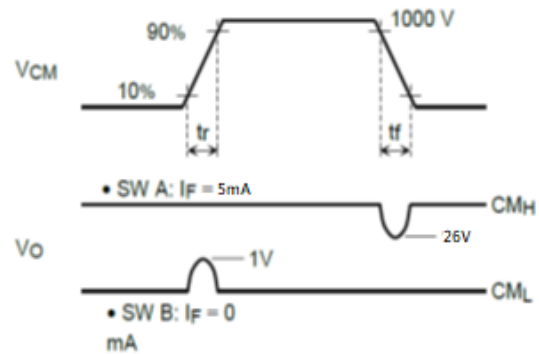
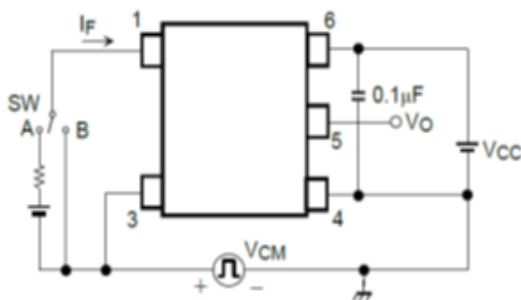


7. t_{pLH} , t_{pHL} , t_r , t_f Measure

$I_F = 5 \text{ mA (P.G)}$
($f=250\text{kHz}$, $\text{duty}=50\%$, $t_r=t_f=5\text{ns}$)



8. C_{MH} , C_{ML} Measure



$$C_{ML} = \frac{1000(\text{v})}{t_r (\mu\text{s})} \quad ; \quad C_{MH} = \frac{1000(\text{v})}{t_f (\mu\text{s})}$$

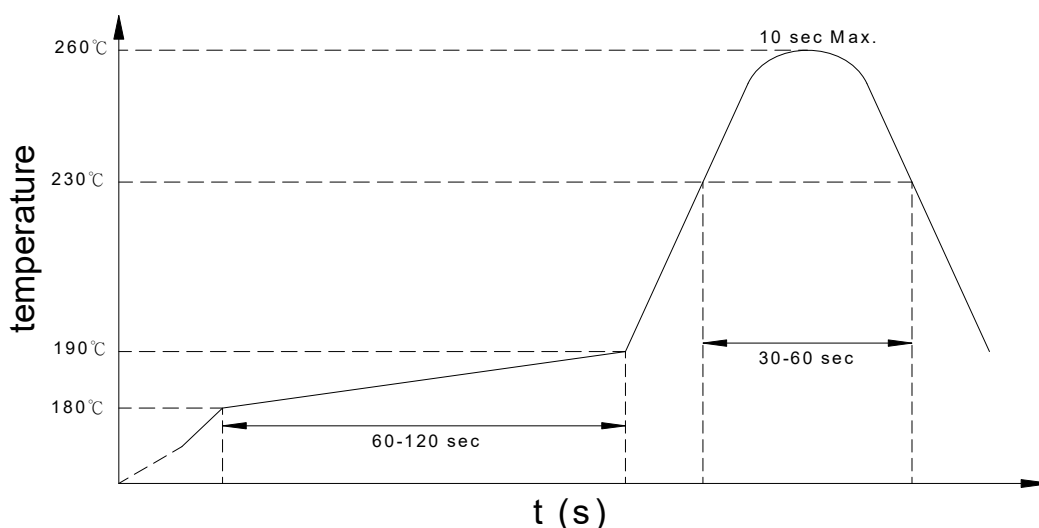
* $C_{ML}(C_{MH})$ is the maximum rate of rise (fall) of the common mode voltage that can be sustained with the output voltage in the low (high) state.

● Recommended Soldering Conditions

(a) Infrared reflow soldering :

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering :

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120°C or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

- **Numbering System**

KPC315 (Y)-(Z)

Notes:

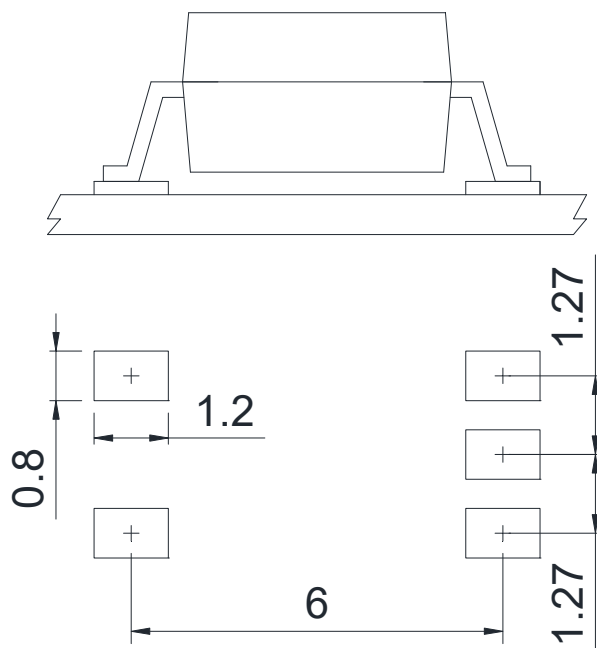
KPC315 = Part No.

Y = Tape and reel option (TLD · TRU)

Z = VDE option (V or None)

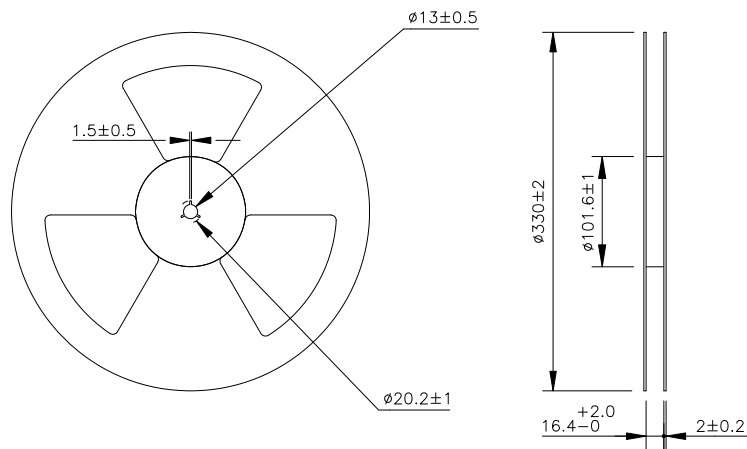
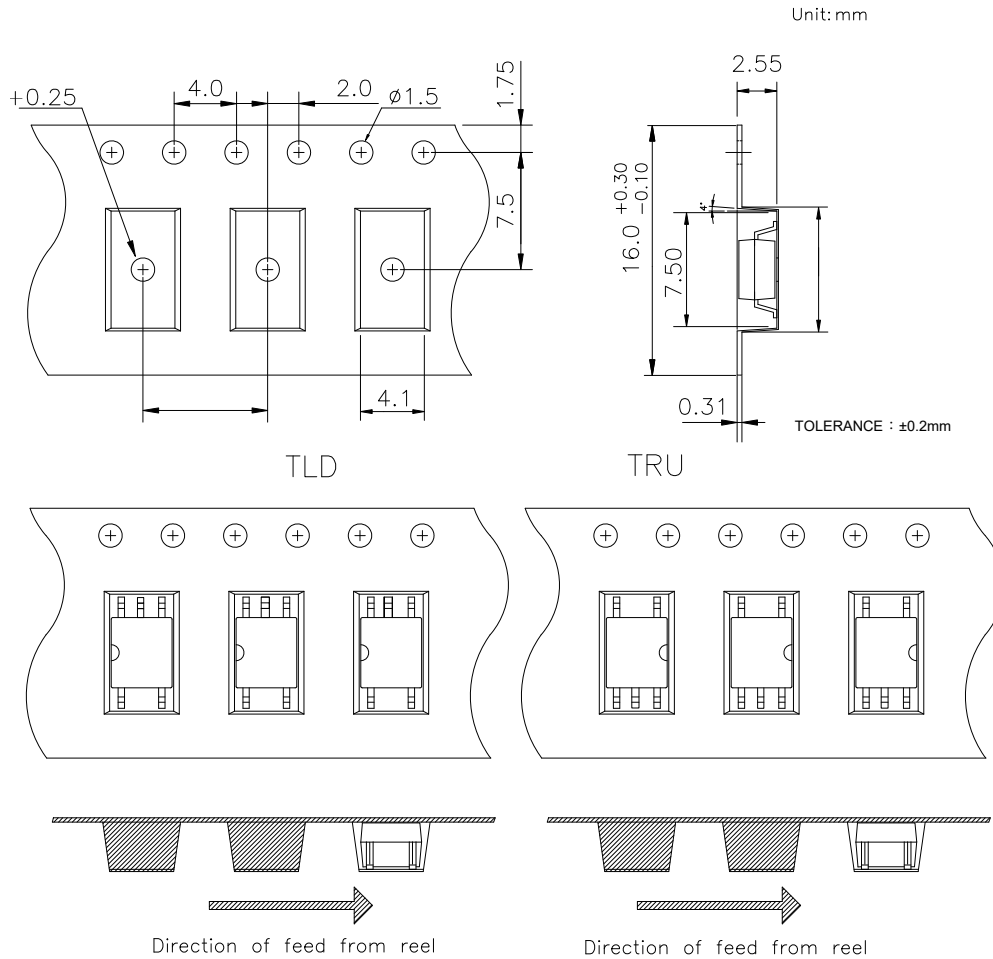
Option	Description	Packing quantity
(TLD)	surface mount type package + TL tape & reel option	3000 units per reel
(TRU)	surface mount type package + TR tape & reel option	3000 units per reel

- **Recommended Pad Layout for Surface Mount Lead Form**



Unit :mm

● SOP Carrier Tape & Reel



- **Application Notice**

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